

**KLT-OIS-AF-IMX258-C V1.2**

**Sony IMX258 MIPI Interface Mise au point automatique 13MP Module de caméra  
Micro stabilisateur de cardan. Plateforme de stabilisation optique d'image (OIS)**



|                                 |                                    |
|---------------------------------|------------------------------------|
| <b>Module de caméra No.</b>     | <b>KLT-OIS-AF-IMX258-C V1.2</b>    |
| <b>Capteur d'image</b>          | IMX258                             |
| <b>Stabilisateur</b>            | Micro stabilisateur de cardan(MGS) |
| <b>EFL</b>                      | 3.05 mm                            |
| <b>F.NO</b>                     | 2.2                                |
| <b>Pixel</b>                    | 4224 x 3192                        |
| <b>Angle de vue</b>             | 87.6°                              |
| <b>Type d'objectif</b>          | 1/3.06 pouce                       |
| <b>Dimensions de l'objectif</b> | 19.00 x 19.00 x 9.9 mm             |
| <b>Taille du module</b>         | 39.00 x 19.00 mm                   |
| <b>Type de module</b>           | Mise au point automatique          |
| <b>Interface</b>                | MIPI                               |
| <b>Modèle d'objectif IMT</b>    | IMT-1A65H005-N                     |

**Référence du connecteur d'accouplement. BAF04-30083-0500**



Connecteur d'accouplement sur la carte principale. Vendu séparément.

# OIS Camera Modules

(OIS = Optical Image Stabilization Platform)

## World's Smallest Gimbal Stabilizer



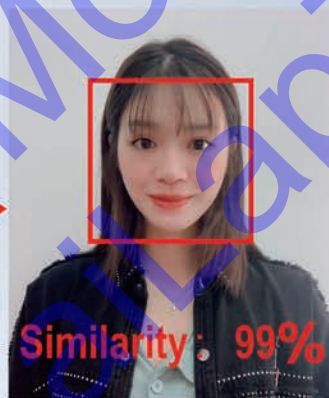
### Core Technologies:

- MGS (micro gimbal stabilizer)  
(The lens and image sensor tilt together)
- $\pm 5$ deg max. compensation angle  
(More than enough for walking and jogging)
- Innovative anti-shaking solutions with 10+ patents
- Integrated design, including a gyroscope and an MGS driver IC

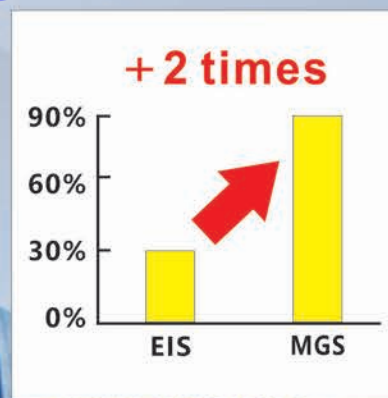
EIS:



MGS:



Face recognition success rate



MGS can significantly reduce blur especially in low-light conditions, and thus support dynamic face recognition and other emerging technologies

### Main Advantages:

- Support horizontal FOV over 100deg
- Support all-glass lens
- 2m+ drop test
- Easy to use
- One-stop anti-shaking solution provider
- Light weight down to 5g
- Small size down to 19×19mm
- Competitive price



Ordering Models



KLT-OIS-USB1A-IMX258 V1.0



KLT-OIS-AF-IMX258-C V1.0

**MGA190 series:**

Size: 19×19×9.9mm  
 Auto Focus MGS  
 Largest FOV: 100deg  
 Max. compensation angle: ±5deg  
 Weight: 5g  
 Support a wide variety of lenses and image sensors  
 Supported sensors:  
 OmniVision OV5640, Sony IMX179 & IMX258

**MGF250 series:**

Size: 25x25x15mm  
 Fixed Focus MGS  
 Largest FOV: 140deg  
 Max. compensation angle: ±5deg  
 Weight: 28g  
 Support a wide variety of lenses and image sensors  
 Supported sensors:  
 Onsemi AR1335, OmniVision OV2718 & OV4689



KLT-OIS-FF-OV4689 V7.0A

| Module                    | Resolution | Sensor   | Focus | DFOV |
|---------------------------|------------|----------|-------|------|
| KLT-OIS-AF-IMX258-C V1.0  | 13 MP OIS  | IMX258-C | Auto  | 87.6 |
| KLT-OIS-USB1A-IMX258 V1.0 | 13 MP OIS  | IMX258   | Auto  | 87.6 |
| KLT-OIS-FF-OV4689 V7.0A   | 4 MP OIS   | OV4689   | Fixed | 122  |

**Product Applications:**



AI face recognition



Body worn camera



Robot



AR/VR smart glasses



Sport DV

## [Product Brief]

Ver.1.0

# IMX258

Diagonal 5.867 mm (Type 1/3.06) 13Mega-Pixel CMOS Image Sensor with Square Pixel for Color Cameras

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### Description

IMX258 is a diagonal 5.867mm (Type 1/3.06) 13 Mega-pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RSTM technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spatially multiplexed exposure technology, high dynamic range still pictures and movies are achievable. It

equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.2 V and 1.8 V for input/output interface and achieves low power consumption.

In addition, this product is designed for use in cellular phone and tablet pc. When using this for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and tablet pc. Consult your Sony sales representative if you have any questions.

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### Functions and Features

- ◆ Back-illuminated and stacked CMOS image sensor Exmor RSTM
- ◆ Phase Detection pixel data output for Phase Detection Auto Focus
- ◆ High Dynamic Range (HDR) mode with raw data output.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR). 4K2K @30fps (Normal / HDR) 1080p @60fps (Normal )
- ◆ Output video format of RAW10/8.
- ◆ Pixel binning readout and V sub-sampling function.
- ◆ Independent flipping and mirroring.
- ◆ CSI-2 serial data output (MIPI 2lane/4lane, Max. 1.3Gbps/lane, D-PHY spec. ver. 1.1 compliant)
- ◆ 2-wire serial communication.
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Dynamic Defect Pixel Correction.
- ◆ Fast mode transition. (on the fly)
- ◆ Dual sensor synchronization operation.
- ◆ 4K bit of OTP ROM for users.
- ◆ Built-in temperature sensor.

**Device Structure**

- ◆ CMOS image sensor
- ◆ Image size : Diagonal 5.867 mm (Type 1/3.06)
- ◆ Total number of pixels : 4224 (H) × 3192 (V) approx. 13.48 M pixels
- ◆ Number of effective pixels : 4224 (H) × 3144 (V) approx. 13.28 M pixels
- ◆ Number of active pixels : 4208 (H) × 3120 (V) approx. 13.13 M pixels
- ◆ Chip size : 5.990 mm (H) × 3.908 mm (V)
- ◆ Unit cell size : 1.12 μm (H) × 1.12 μm (V)
- ◆ Substrate material : Silicon

System block diagram



**Exmor RS**

\* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.